

# **CD4070B, CD4077B**

## **CMOS Quad Exclusive-OR and Exclusive-NOR Gate**

### **Features**

- High-Voltage Types (20V Rating)
- CD4070B - Quad Exclusive-OR Gate
- CD4077B - Quad Exclusive-NOR Gate
- Medium Speed Operation
  - $t_{PHL}, t_{PLH} = 65\text{ns}$  (Typ) at  $V_{DD} = 10\text{V}$ ,  $C_L = 50\text{pF}$
- 100% Tested for Quiescent Current at 20V
- Standardized Symmetrical Output Characteristics
- 5V, 10V and 15V Parametric Ratings
- Maximum Input Current of  $1\mu\text{A}$  at 18V Over Full Package Temperature Range
  - $100\text{nA}$  at 18V and  $25^\circ\text{C}$
- Noise Margin (Over Full Package Temperature Range)
  - 1V at  $V_{DD} = 5\text{V}$ , 2V at  $V_{DD} = 10\text{V}$ , 2.5V at  $V_{DD} = 15\text{V}$
- Meets All Requirements of JEDEC Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

### **Applications**

- Logical Comparators
- Adders/Subtractors
- Parity Generators and Checkers

### **Description**

The Harris CD4070B contains four independent Exclusive-OR gates. The Harris CD4077B contains four independent Exclusive-NOR gates.

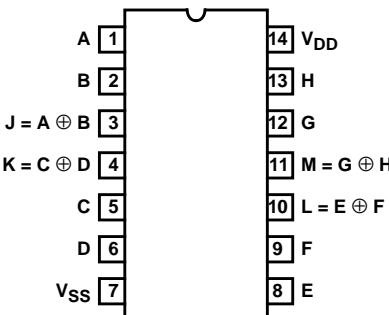
The CD4070B and CD4077B provide the system designer with a means for direct implementation of the Exclusive-OR and Exclusive-NOR functions, respectively.

### **Ordering Information**

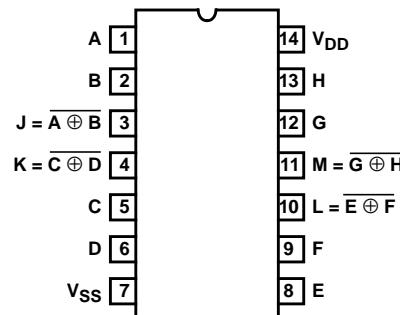
PART NUMBER	TEMP. RANGE ( $^\circ\text{C}$ )	PACKAGE	PKG. NO.
CD4070BE	-55 to 125	14 Ld PDIP	E14.3
CD4077BE	-55 to 125	14 Ld PDIP	E14.3
CD4070BF	-55 to 125	14 Ld CERDIP	F14.3
CD4077BF	-55 to 125	14 Ld CERDIP	F14.3
CD4070BM	-55 to 125	14 Ld SOIC	M14.15
CD4077BM	-55 to 125	14 Ld SOIC	M14.15

### **Pinouts**

**CD4070B**  
(PDIP, CERDIP, SOIC)  
TOP VIEW

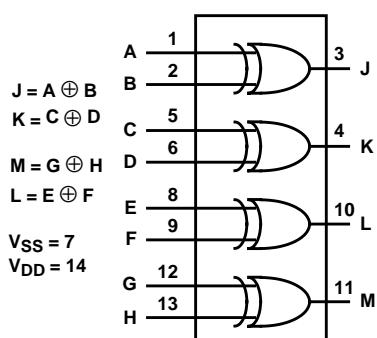


**CD4077B**  
(PDIP, CERDIP, SOIC)  
TOP VIEW

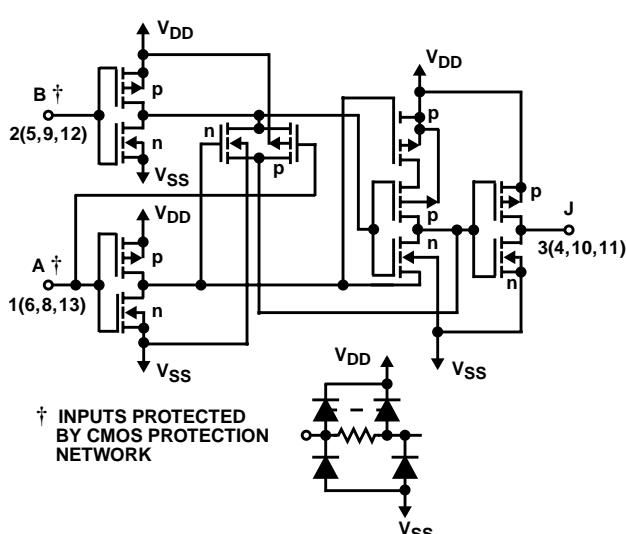
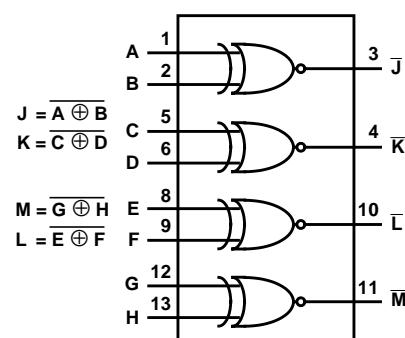


### Functional Diagrams

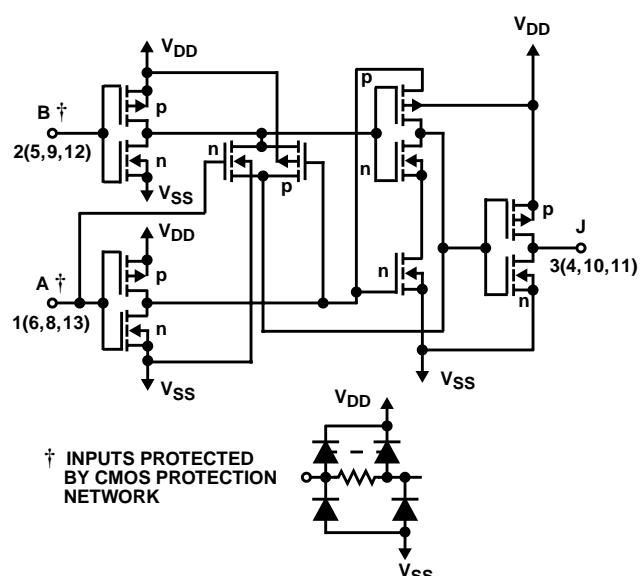
**CD4070B**



**CD4077B**



**FIGURE 1. SCHEMATIC DIAGRAM FOR CD4070B  
(1 OF 4 IDENTICAL GATES)**



**FIGURE 2. SCHEMATIC DIAGRAM FOR CD4077B  
(1 OF 4 IDENTICAL GATES)**

**CD4070B TRUTH TABLE (1 OF 4 GATES)**

A	B	J
0	0	0
1	0	1
0	1	1
1	1	0

NOTE:

1 = High Level

0 = Low Level

$J = A \oplus B$

**CD4077B TRUTH TABLE (1 OF 4 GATES)**

A	B	J
0	0	1
1	0	0
0	1	0
1	1	1

NOTE:

1 = High Level

0 = Low Level

$J = A \oplus B$

**Absolute Maximum Ratings**

DC Supply Voltage Range ( $V_{DD}$ ) ..... -0.5V to 20V  
 Input Voltage Range, All Inputs ..... -0.5V to  $V_{DD}$  0.5V  
 DC Input Current .....  $\pm 10\text{mA}$

**Operating Conditions**

Temperature Range ( $T_A$ ) ..... -55°C to 125°C  
 Supply Voltage Range (Typical) ..... 3V to 18V

*CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.*

NOTE:

1.  $\theta_{JA}$  is measured with the component mounted on an evaluation PC board in free air.

**Thermal Information**

	$\theta_{JA}$ (°C/W)	$\theta_{JC}$ (°C/W)
PDIP Package	90	N/A
CERDIP Package	95	38
SOIC Package	175	N/A

Maximum Junction Temperature (Hermetic Package or Die) 175°C  
 Maximum Junction Temperature (Plastic Package) ..... 150°C  
 Maximum Storage Temperature Range ..... -65°C to 150°C

**DC Electrical Specifications**

PARAMETER	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)						UNITS
				-55	-40	85	125	25		
	$V_O$ (V)	$V_{IN}$ (V)	$V_{DD}$ (V)	MIN	TYP	MAX				
Quiescent Device Current $I_{DD}$ Max	-	0, 5	5	0.25	0.25	7.5	7.5	-	0.01	0.25
	-	0, 10	10	0.5	0.5	15	15	-	0.01	0.5
	-	0, 15	15	1	1	30	30	-	0.01	1
	-	0, 20	20	5	5	150	150	-	0.02	5
Output Low (Sink) Current $I_{OL}$ Min	0.4	0, 5	5	0.64	0.61	0.42	0.36	0.51	1	-
	0.5	0, 10	10	1.6	1.5	1.1	0.9	1.3	2.6	-
	1.5	0, 15	15	4.2	4	2.8	2.4	3.4	6.8	-
Output High (Source) Current $I_{OH}$ Min	4.6	0, 5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	-
	2.5	0, 5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-
	9.5	0, 10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	-
	13.5	0, 15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	-
Output Voltage: Low Level, $V_{OL}$ Max	-	0, 5	5	0.05	0.05	0.05	0.05	-	0	0.05
	-	0, 10	10	0.05	0.05	0.05	0.05	-	0	0.05
	-	0, 15	15	0.05	0.05	0.05	0.05	-	0	0.05
Output Voltage: High Level, $V_{OH}$ Min	-	0, 5	5	4.95	4.95	4.95	4.95	4.95	5	-
	-	0, 10	10	9.95	9.95	9.95	9.95	9.95	10	-
	-	0, 15	15	14.95	14.95	14.95	14.95	14.95	15	-
Input Low Voltage, $V_{IL}$ Max	0.5, 4.5	-	5	1.5	1.5	1.5	1.5	-	-	1.5
	1, 9	-	10	3	3	3	3	-	-	3
	1.5, 13.5	-	15	4	4	4	4	-	-	4
Input High Voltage, $V_{IH}$ Min	0.5, 4.5	-	5	3.5	3.5	3.5	3.5	-	-	V
	1, 9	-	10	7	7	7	7	-	-	V
	1.5, 13.5	-	15	11	11	11	11	-	-	V
Input Current, $I_{IN}$ Max	-	0, 18	18	$\pm 0.1$	$\pm 0.1$	$\pm 1$	$\pm 1$	-	$\pm 10^{-5}$	$\pm 0.1$

**AC Electrical Specifications**  $T_A = 25^\circ\text{C}$ , Input  $t_r, t_f = 20\text{ns}$ ,  $C_L = 50\text{pF}$ ,  $R_L = 200\text{k}\Omega$ 

PARAMETER	SYMBOL	TEST CONDITIONS		LIMITS ON ALL TYPES		UNITS
		$V_{DD}$ (V)	TYP	MAX		
Propagation Delay Time	$t_{PHL}, t_{PLH}$	5	140	280	ns	
		10	65	130	ns	
		15	50	100	ns	
Transition Time	$t_{THL}, t_{TLH}$	5	100	200	ns	
		10	50	100	ns	
		15	40	80	ns	
Input Capacitance	$C_{IN}$	Any Input	5	7.5	pF	

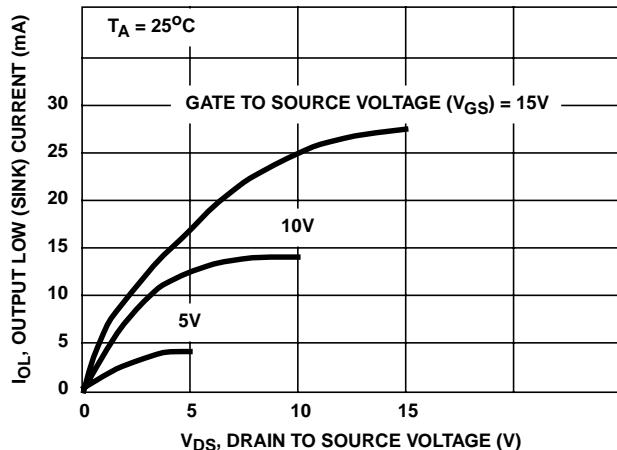
**Typical Performance Curves**

FIGURE 3. TYPICAL OUTPUT LOW (SINK) CURRENT CHARACTERISTICS

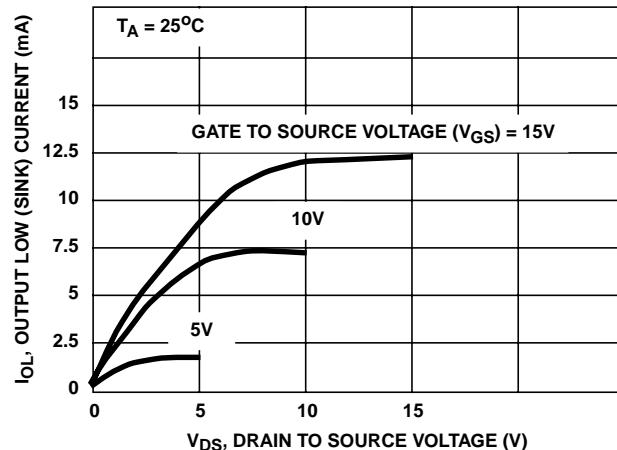


FIGURE 4. MINIMUM OUTPUT LOW (SINK) CURRENT CHARACTERISTICS

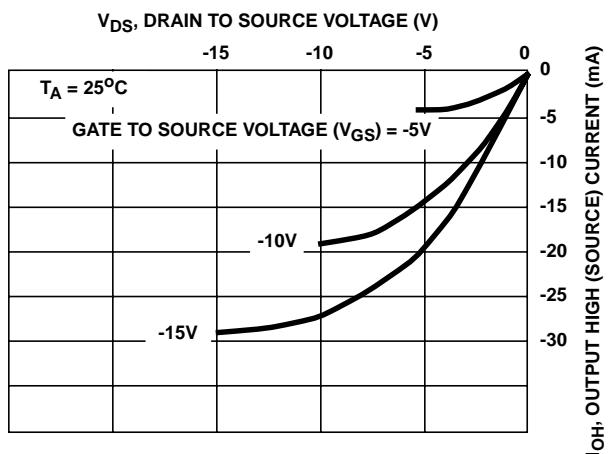


FIGURE 5. TYPICAL OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

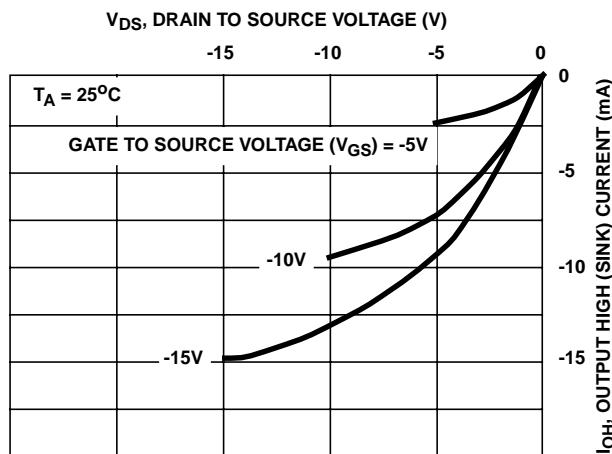
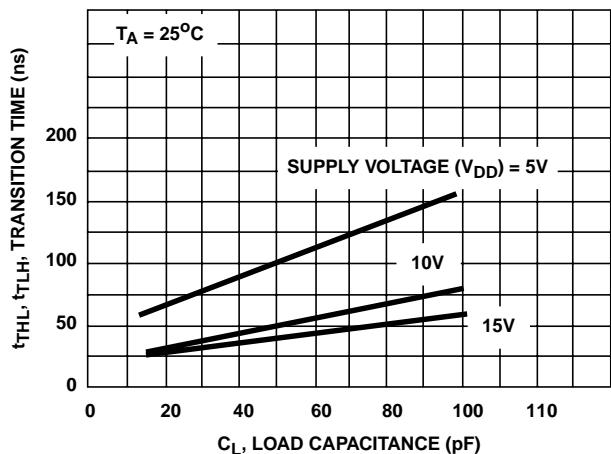
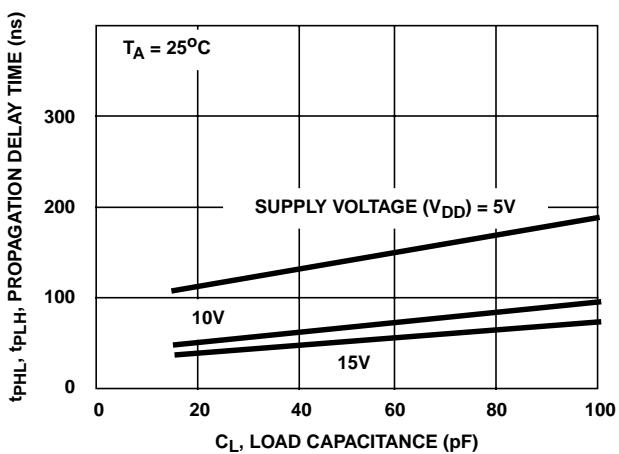


FIGURE 6. MINIMUM OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

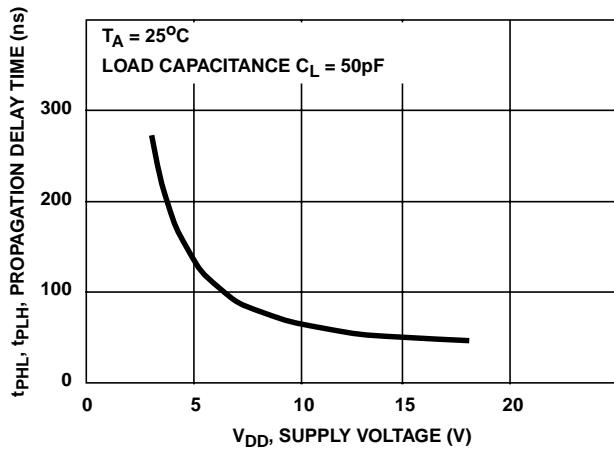
**Typical Performance Curves (Continued)**



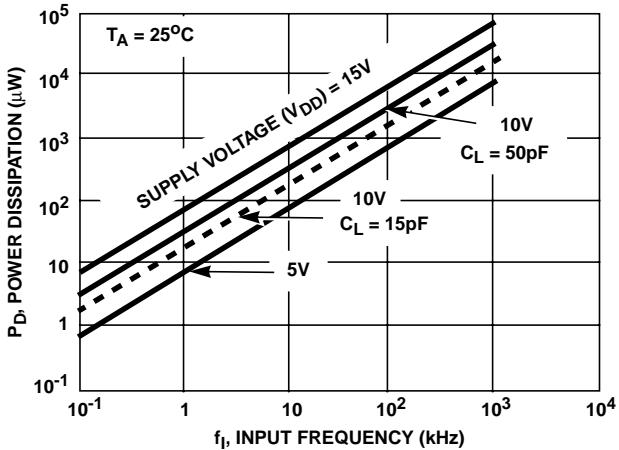
**FIGURE 7. TYPICAL TRANSITION TIME AS A FUNCTION OF LOAD CAPACITANCE**



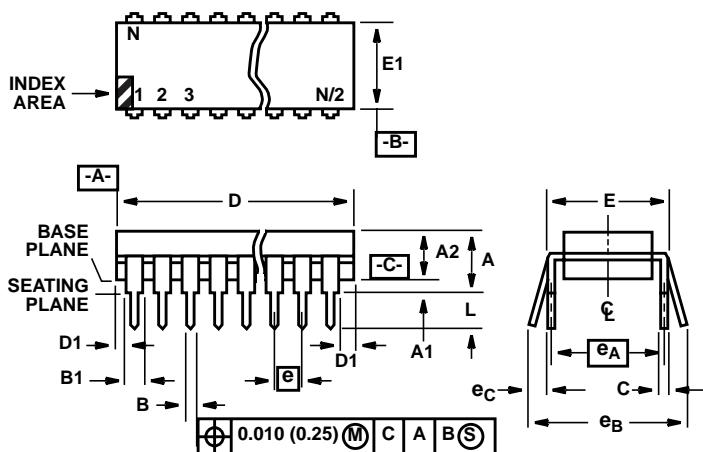
**FIGURE 8. TYPICAL PROPAGATION DELAY TIME AS A FUNCTION OF LOAD CAPACITANCE**



**FIGURE 9. TYPICAL PROPAGATION DELAY TIME AS A FUNCTION OF SUPPLY VOLTAGE**



**FIGURE 10. TYPICAL DYNAMIC POWER DISSIPATION AS A FUNCTION OF INPUT FREQUENCY**

**Dual-In-Line Plastic Packages (PDIP)**

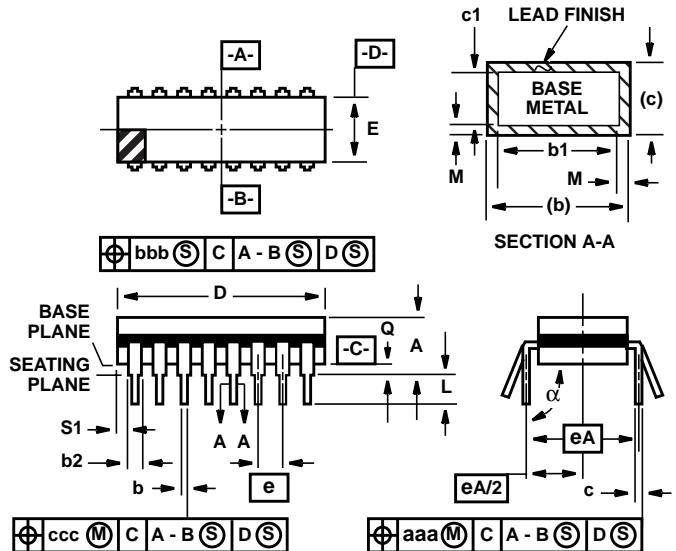
## NOTES:

1. Controlling Dimensions: INCH. In case of conflict between English and Metric dimensions, the inch dimensions control.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication No. 95.
4. Dimensions A, A1 and L are measured with the package seated in JEDEC seating plane gauge GS-3.
5. D, D1, and E1 dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 inch (0.25mm).
6. E and  $e_A$  are measured with the leads constrained to be perpendicular to datum  $-C-$ .
7.  $e_B$  and  $e_C$  are measured at the lead tips with the leads unconstrained.  $e_C$  must be zero or greater.
8. B1 maximum dimensions do not include dambar protrusions. Dambar protrusions shall not exceed 0.010 inch (0.25mm).
9. N is the maximum number of terminal positions.
10. Corner leads (1, N, N/2 and N/2 + 1) for E8.3, E16.3, E18.3, E28.3, E42.6 will have a B1 dimension of 0.030 - 0.045 inch (0.76 - 1.14mm).

**E14.3 (JEDEC MS-001-AA ISSUE D)  
14 LEAD DUAL-IN-LINE PLASTIC PACKAGE**

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.210	-	5.33	4
A1	0.015	-	0.39	-	4
A2	0.115	0.195	2.93	4.95	-
B	0.014	0.022	0.356	0.558	-
B1	0.045	0.070	1.15	1.77	8
C	0.008	0.014	0.204	0.355	-
D	0.735	0.775	18.66	19.68	5
D1	0.005	-	0.13	-	5
E	0.300	0.325	7.62	8.25	6
E1	0.240	0.280	6.10	7.11	5
e	0.100 BSC		2.54 BSC		-
$e_A$	0.300 BSC		7.62 BSC		6
$e_B$	-	0.430	-	10.92	7
L	0.115	0.150	2.93	3.81	4
N	14		14		9

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**Ceramic Dual-In-Line Frit Seal Packages (CERDIP)**

## NOTES:

- Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark.
- The maximum limits of lead dimensions b and c or M shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
- Dimensions b1 and c1 apply to lead base metal only. Dimension M applies to lead plating and finish thickness.
- Corner leads (1, N, N/2, and N/2+1) may be configured with a partial lead paddle. For this configuration dimension b3 replaces dimension b2.
- This dimension allows for off-center lid, meniscus, and glass overrun.
- Dimension Q shall be measured from the seating plane to the base plane.
- Measure dimension S1 at all four corners.
- N is the maximum number of terminal positions.
- Dimensioning and tolerancing per ANSI Y14.5M - 1982.
- Controlling dimension: INCH.

**F14.3 MIL-STD-1835 GDIP1-T14 (D-1, CONFIGURATION A)  
14 LEAD CERAMIC DUAL-IN-LINE FRIT SEAL PACKAGE**

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.200	-	5.08	-
b	0.014	0.026	0.36	0.66	2
b1	0.014	0.023	0.36	0.58	3
b2	0.045	0.065	1.14	1.65	-
b3	0.023	0.045	0.58	1.14	4
c	0.008	0.018	0.20	0.46	2
c1	0.008	0.015	0.20	0.38	3
D	-	0.785	-	19.94	5
E	0.220	0.310	5.59	7.87	5
e	0.100 BSC		2.54 BSC		-
eA	0.300 BSC		7.62 BSC		-
eA/2	0.150 BSC		3.81 BSC		-
L	0.125	0.200	3.18	5.08	-
Q	0.015	0.060	0.38	1.52	6
S1	0.005	-	0.13	-	7
$\alpha$	$90^\circ$	$105^\circ$	$90^\circ$	$105^\circ$	-
aaa	-	0.015	-	0.38	-
bbb	-	0.030	-	0.76	-
ccc	-	0.010	-	0.25	-
M	-	0.0015	-	0.038	2, 3
N	14		14		8

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